

ABSTRACT

ANGLED FLYING LEAD WIRE BONDING PROCESS

A method is described having the steps of providing a surface having a plurality of wire bondable locations; wire bonding a wire to each of the wire bondable locations using a wire capillary tool; controlling the position of the capillary tool with respect to the substrate; after forming a wire bond of the wire to the wire bondable location moving the capillary tool relative to the surface as the capillary tool is moved away from the surface to form a wire having a predetermined shape.